# 100% Material Declaration Data Sheet for 7 Series FGG676 Package

PK592 (v1.0) February 1, 2013

## Average Weight: 2.9810 g

| Component | Substance Description | CAS Number or Description | Percentage of Component | Use in Product | Component Weight/ Substance Weight (grams) | Component Percent of Total |
|---|---|---|---|---|---|---|
| **Silicon Die** | | | | | **0.048068** | **1.612** |
| | Silicon | 7440-21-3 | 100.00 | | 0.048068 | |
| **Die Attach** | | | | | **0.008755** | **0.294** |
| | Silver | 7440-22-4 | 77.50 | | 0.006785 | |
| | Bismaleimide monomer | Trade Secret | 15.00 | | 0.001313 | |
| | Acrylate monomer | Trade Secret | 7.50 | | 0.000657 | |
| **Mold Compound** | | | | | **1.497385** | **50.231** |
| | Epoxy Resin | Trade secret | 5.00 | | 0.074869 | |
| | Phenol Resin | Trade secret | 3.00 | | 0.044922 | |
| | Phenol Novolac | 9003-35-4 | 3.00 | | 0.044922 | |
| | Metal Hydroxide | Trade Secret | 3.00 | | 0.044922 | |
| | Carbon black | 1333-86-4 | 0.30 | | 0.004492 | |
| | Silica fused | 60676-86-0 | 70.40 | | 1.054158 | |
| | Silica Dioxide | 7631-86-9 | 15.00 | | 0.224608 | |
| | Silica, crystalline | 14808-60-7 | 0.30 | | 0.004492 | |
| **Copper Wire** | | | | | **0.007404** | **0.248** |
| | Copper | 7440-50-8 | 98.20 | | 0.007271 | |
| | Palladium | 7440-05-3 | 1.80 | | 0.000133 | |
| **Solder Ball** | | | | | **0.564707** | **18.944** |
| | Tin | 7440-31-5 | 96.50 | | 0.544942 | |
| | Silver | 7440-22-4 | 3.00 | | 0.016941 | |
| | Copper | 7440-50-8 | 0.50 | | 0.002824 | |

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| Component | Substance Description | CAS Number or Description | Percentage of Component | Use in Product | Component Weight/ Substance Weight (grams) | Component Percent of Total |
|---|---|---|---|---|---|---|
| **Substrate** | | | | | **0.854681** | **28.671** |
| | Copper | 7440-50-8 | 18.90 | | 0.161535 | |
| | Nickel | 7440-02-0 | 6.80 | | 0.058118 | |
| | Gold | 7440-57-5 | 0.81 | | 0.006923 | |
| | Glass fiber | 65997-17-3 | 21.12 | | 0.180509 | |
| | Non halogen fire retardant | NA | 0.01 | | 0.000085 | |
| | BT core | 105391-33-1<br>25722-66-1<br>9003-36-5<br>21645-51-2<br>7440-50-8 | 43.38 | | 0.370761 | |
| | Solder mask | 147-14-8<br>7727-43-7<br>7631-86-9<br>14807-96-6<br>112-15-2<br>34590-94-8<br>103429-90-9<br>64742-94-5<br>25551-13-7 | 8.98 | | 0.076750 | |

## Revision History

The following table shows the revision history for this document.

| Date | Version | Description of Revisions |
|---|---|---|
| 02/01/2013 | 1.0 | Xilinx Initial Release |

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